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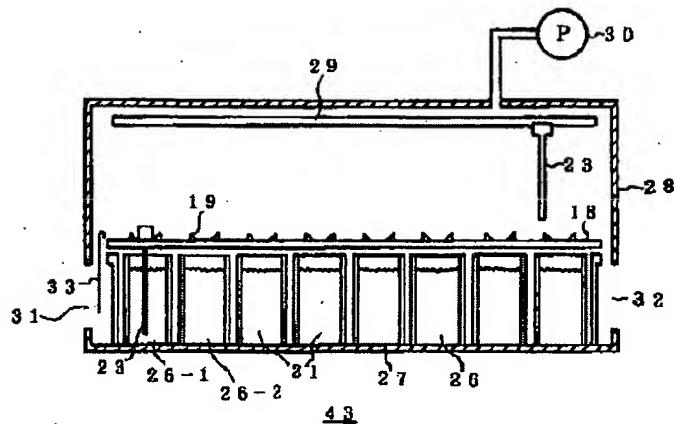
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**TITLE** : METHOD FOR PRODUCING PRINTED  
WIRING BOARD, AND PLATING  
APPARATUS FOR INTERLAYER  
CONTACT HOLE OF PRINTED WIRING  
BOARD



**ABSTRACT :** PROBLEM TO BE SOLVED: To produce a printed wiring board for ultrahigh integration circuit with high yield by forming a uniform plating film on the inner wall face/even of a fine blind via hole corresponding to a fine pattern wiring circuit in a multilayer printed wiring board.

**SOLUTION:** A large number of single board plating apparatus 26 are arranged on the floor face in a non-airtight chamber 28. A printed wiring board 23 is plated, while being hooked to a support 18 disposed above the carry-in/ carry-out opening 24 of the printed wiring board 23 in the array of plating apparatus 26. When the support 18 is oscillated, a plating liquid flow is generated and degassing takes place. The non-airtight chamber 28 is coupled with an exhaust pump 30 and plating is performed, while setting a pressure reduced atmosphere in the non-airtight chamber 28.

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